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**Migrating from STM32L15/6xxD to STM32L15/6xxE**

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**Introduction**

To ease the development of STM32 microcontroller applications, it is important to be able to smoothly replace one microcontroller type with another from the same product family. The purpose of this technical note is to help users with the migration from an STM32L15/6xxD (348KB Flash) device to an STM32L15/6xxE (512KB Flash) device. This document includes the relevant information for users.

Prior to migrating an application, users need to analyze the hardware migration, the peripheral migration and the firmware migration. To better understand the information included in this technical note, users should be familiar with the STM32L1 microcontroller family.

For additional information, please refer to the STM32L100xx, STM32L151xx, STM32L152xx and STM32L162xx advanced ARM<sup>®</sup>-based 32-bit MCUs reference manual RM0038 in which STM32L15/6xxD is 'Cat.4' device, STM32L15/6xxE is 'Cat.5' device, and to the STM32L15/6xxD, STM32L15/6xxE datasheets. Documents are available for download from the company website at [www.st.com/stm32](http://www.st.com/stm32).

*Table 1* lists the STM32 microcontrollers concerned by this technical note.

**Table 1. Applicable products**

Type	Reference products
Microcontrollers	STM32L151QD, STM32L151RD, STM32L151VD, STM32L151ZD, STM32L152QD, STM32L152RD, STM32L152VD, STM32L152ZD, STM32L162QD, STM32L162RD, STM32L162VD, STM32L162ZD, STM32L151QE, STM32L151RE, STM32L151VE, STM32L151ZE, STM32L152QE, STM32L152RE, STM32L152VE, STM32L152ZE, STM32L162RE, STM32L162VE, STM32L162ZE.

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# 1 Codification/package changes

*Table 2* presents the list of references, part numbers and packages for the STM32L15/6xxD and STM32L15/6xxE products.

**Table 2. STM32L15/6xxD and STM32L15/6xxE codification summary**

Device description	Reference product	Part number	Packages
Up to: STM32L15/6xxD - 384KB Flash 48KB RAM 12KB EEPROM	STM32L151xD STM32L152xD STM32L162xD	STM32L151QD STM32L151RD STM32L151VD STM32L151ZD STM32L152QD STM32L152RD STM32L152VD STM32L152ZD STM32L162RD STM32L162VD STM32L162ZD	LQFP144 LQFP100 LQFP64 UFBGA132 WLCSP64
Up to: STM32L15/6xxE - 512KB Flash 80KB RAM 16KB EEPROM	STM32L151xE STM32L152xE STM32L162xE	STM32L151QE STM32L151RE STM32L151VE STM32L151ZE STM32L152QE STM32L152RE STM32L152VE STM32L152ZE STM32L162RE STM32L162VE STM32L162ZE	LQFP144 LQFP100 LQFP64 UFBGA132 WLCSP104

The changes and similarities in the codification/packages in STM32L15/6xxE versus STM32L15/6xxD are the following:

- the packages are the same except the WLCSP packages,
- the pinout is the same except for WLCSP packages.

## 2 Hardware migration

The STM32L15/6xxD and STM32L15/6xxE devices are produced in the same packages and are pin-to-pin compatible except for WLCSP packages. All common peripherals share the same pins.

The FSMC and SDIO and OPAMP3 peripherals are not present in STM32L15/6xxE devices. In case FSMC or SDIO or the OPAMP3 were used in STM32L15/6xxD and are no longer needed in the STM32L15/6xxE-based new design, some hardware changes are needed when migrating from STM32L15/6xxD to STM32L15/6xxE devices.

In case FSMC or SDIO or OPAMP3 peripheral were not used in STM32L15/6xxD hardware design, the transition from the STM32L15/6xxD device to the STM32L15/6xxE device is simple. The device can be replaced without any hardware change on the application PCB.

### 3 Peripheral migration

*Table 3* lists the main product peripherals and system features for both product sets. The common peripherals are supported with the dedicated firmware library (from version 1.3.0) without any modification. Users can change the instance and all the related features (clock configuration, pin configuration, interrupt/DMA request).

The main peripherals changes are described in *Section 3.1: Main peripherals/system changes*. The changes which are also needed in the development tools configuration are described in *Section 4: Development tool adaptations*.

*Table 3* presents the differences between STM32L15/6xxD and STM32L15/6xxE devices regarding the peripherals and system differences, as well as the impact on the software.

**Table 3. STM32L15/6xxD and STM32L15/6xxE device difference summary**

Function	STM32L15/6xxD	STM32L15/6xxE	Behavior / impact to software
Core @ 32MHz	ARM® Cortex®-M3	ARM® Cortex®-M3	-
Max DMIPS/MHz	1.25	1.25	-
Flash [KB]	Dual bank 2 x 192 KB	Dual bank 2 x 256 KB	Enhancement. More complex applications can be stored into the Flash memory.
RAM [KB]	48	80	Enhancement. The application can use larger RAM memory space.
EEPROM [KB]	Dual bank 2 x 6 KB	Dual bank 2 x 8 KB	Enhancement. The application can use larger EEPROM memory space.
Backup registers [B]	128	128	-
Flash interface [bits]	64/32	64/32	-
Bootloader	USART/USB	USART/USB	-
DMA / channels	2 / 12ch	2 / 12ch	-
USART/UART	3 / 2	3 / 2	-
SPI / I2S	3 / 2	3 / 2	-
I2C	2	2	-
USB 2.0	1 x FS	1 x FS	-
LCD [seg x com]	8 x 40	8 x 40	-
LCD rails decoupling	NO	NO	-
TIMER [32-bit/16-bit/Lite]	1/6/2	1/6/2	-
IWDG/WWDG	1/1	1/1	-

Table 3. STM32L15/6xxD and STM32L15/6xxE device difference summary (continued)

Function	STM32L15/6xxD	STM32L15/6xxE	Behavior / impact to software
<b>Clock</b>	HSI/HSE/LSI/LSE CSS on HSE/LSE	HSI/HSE/LSI/LSE CSS on HSE/LSE	-
<b>HSI/HSI clock trimming</b>	+/- 1%	+/- 1%	-
<b>RTC version</b>	RTC V2.0	RTC V2.0	-
<b>DAC</b>	2	2	-
<b>ADC (total / fast channels)</b>	1 (40 / 6)	1 (40 / 6)	-
<b>Comparator</b>	2	2	-
<b>Touch sensing [channels]</b>	34	34	-
<b>Temperature sensor</b>	YES	YES	-
<b>Internal voltage reference</b>	YES	YES	-
<b>Unique ID</b>	YES	YES	-
<b>MCO</b>	YES	YES	-
<b>FSMC</b>	YES	NO	FSMC is not present. Hardware and software must be adapted in STM32L15/6xxE if FSMC is used in STM32L15/6xxD.
<b>SDIO</b>	YES	NO	SDIO is not present. Hardware and software must be adapted in STM32L15/6xxE if SDIO is used in STM32L15/6xxD.
<b>Operational amplifier</b>	3	2	OPAMP3 is not present. Hardware and software must be adapted in STM32L15/6xxE if OPAMP3 is used in STM32L15/6xxD.

## 3.1 Main peripherals/system changes

Some system properties and peripherals configuration are changed in the STM32L15/6xxE device. The following sections describe these changes.

### 3.1.1 Memory space increase

The memory areas are increased in the STM32L15/6xxE device as follows:

- Flash: from 384 KB to 512 KB
- RAM: from 48 KB to 80 KB
- EEPROM: from 12 KB to 16 KB

The memory increases permit to use STM32L15/6xxE device in more complex applications.

### 3.1.2 FSMC removal

The flexible static memory controller (FSMC) is not present in the STM32L15/6xxE device. The software and hardware must be adapted when migrating to STM32L15/6xxE device in case the FSMC peripheral is used in the hardware design using the STM32L15/6xxD device.

The STM32L15/6xxE features more Flash memory (512KB) than the STM32L15/6xxD (384 KB). This additional memory can replace the need for some external memory connected through FSMC interface.

### 3.1.3 SDIO removal

The secure digital input/output interface (SDIO) is not present in the STM32L15/6xxE device. The software and hardware must be adapted when migrating to STM32L15/6xxE device in case the SDIO peripheral is used in the hardware design using the STM32L15/6xxD device.

The STM32L15/6xxE features more Flash memory (512KB) than STM32L15/6xxD (384KB) and this additional memory can replace the need for an external memory connected through the SDIO interface.

### 3.1.4 OPAMP3 removal

One operational amplifier (OPAMP3) is not present in the STM32L15/6xxE device. The software and hardware must be adapted when migrating to STM32L15/6xxE device in case the OPAMP3 peripheral is used in the hardware design using the STM32L15/6xxD device.

## 3.2 Device limitation changes/updates

The errata sheet on STM32L15/6xxE devices is available on the company website at [www.st.com](http://www.st.com). Several limitations that had been reported for the STM32L15/6xxD have been solved, while other limitations have been introduced. This section describes the changes in the device limitations.

Please refer to STM32L15/6xxD errata sheet and STM32L15/6xxE errata sheet for details on the device limitations.



### 3.2.1 STM32L15/6xxD-specific limitations

The following limitations that apply to STM32L15/6xxD devices do not apply to STM32L15/6xxE devices:

- Missing analog switch on GPIO PC10,
- Pull-up on PB7 when configured in analog mode,
- Debugging Stop mode with WFE entry.

### 3.2.2 STM32L15/6xxE-specific limitations

The following limitations which do not concern the STM32L15/6xxD devices have been introduced for STM32L15/6xxE devices:

- Erase/program operations partially executed if used multi-cycle STRD instruction is interrupted,
- Data EEPROM cycling is limited to 100 kcycles instead of 300 kcycles.

## 4 Development tool adaptations

When migrating from STM32L15/6xxD to STM32L15/6xxE some changes in the development tools are necessary. Following the change of device identifier (DEV\_ID) and some peripherals changes with the addition of new features, it has been necessary to upgrade the development tools as detailed hereafter.

1. DEV\_ID changes:
  - In STM32L15/6xxD devices, DEV\_ID = 0x436
  - In STM32L15/6xxE devices, DEV\_ID = 0x437
  - If the software or programming tool is using DEV\_ID[11:0] field (in DBGMCU\_IDCODE register) then the relevant changes must be applied in the software or tool.
2. Changes in the development tool configurations:
  - a) IAR - install the latest version or apply the patch provided by ST support team to support the STM32L15/6xxE device, and change the device type in the configuration.
  - b) Keil - install the latest version that supports the STM32L15/6xxE device, change the device type in the configuration, and change the ST-LINK programming algorithm.
  - c) Others - install the latest version that supports the STM32L15/6xxE device, and change the device type in the configuration.
3. STM32L1xx standard peripherals library update:

STM32L15/6xxE devices are supported in the latest version of STM32L1xx standard peripherals library. Make sure to use the latest version of STM32L1xx standard peripherals library to use the STM32L15/6xxE device features.

  - a) Define the macro STM32L1XX\_XL and use in the project the *startup\_stm32l1xx\_xl.s* file.
  - b) Rebuild the existing project with the new library so it can be run on STM32L15/6xxE devices.
4. Programming tool adaptations:

In the programming tool configurations (for example ST-LINK with the related software) the device type must be changed to correctly program the new STM32L15/6xxE devices.

Use the latest ST Visual Programmer (STVP) or the latest ST-LINK utility which support the STM32L15/6xxE devices (both are available at [www.st.com/stm32](http://www.st.com/stm32)).

## 5 Consumption comparison

The STM32L15/6xxE devices feature less dynamic consumption than the STM32L15/6xxD devices, due to the advanced manufacturing technology. The power consumptions in low-power modes are on similar levels.

*Table 4* shows the differences in power consumption between the devices in the various operating modes.

**Table 4. Consumption difference summary**

Parameters (all at $V_{DD}=3V$ )	STM32L15/6xxD	STM32L15/6xxE
Full speed from flash (32 MHz in HSI)	325 $\mu A/MHz$	270 $\mu A/MHz$
MSI clock from flash (4.2 MHz)	230 $\mu A/MHz$	195 $\mu A/MHz$
Low-power Run from RAM @ 32 kHz	12.5 $\mu A$	11.0 $\mu A$
Low-power sleep from RAM @ 32 kHz	6.1 $\mu A$	5.5 $\mu A$
Stop mode	476 nA	560 nA
Stop mode with RTC on LSI	1.35 $\mu A$	1.40 $\mu A$
Standby mode	305 nA	290 nA
Standby mode with RTC on LSI	1.16 $\mu A$	1.04 $\mu A$

## 6 Revision history

Table 5. Document revision history

Date	Revision	Changes
23-May-2014	1	Initial release.

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